### PROCEEDINGS OF SPIE

# Laser-based Micro- and Nanoprocessing XVI

Akira Watanabe Rainer Kling Editors

22–27 January 2022 San Francisco, California, United States

20-24 February 2022 ONLINE

Sponsored and Published by SPIE

Volume 11989 The papers in this volume were part of the technical conference cited on the cover and title page. Papers were selected and subject to review by the editors and conference program committee. Some conference presentations may not be available for publication. Additional papers and presentation recordings may be available online in the SPIE Digital Library at SPIEDigitalLibrary.org.

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Author(s), "Title of Paper," in Laser-based Micro- and Nanoprocessing XVI, edited by Akira Watanabe, Rainer Kling, Proc. of SPIE 11989, Seven-digit Article CID Number (DD/MM/YYYY); (DOI URL).

ISSN: 0277-786X

ISSN: 1996-756X (electronic)

ISBN: 9781510648494

ISBN: 9781510648500 (electronic)

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA Telephone +1 360 676 3290 (Pacific Time) SPIE.org

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